

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3660753

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	SUSS MICROTEC, INC.	03/10/2011
RECEIVING PARTY DATA		
Name:	SUSS MICROTEC LITHOGRAPHY GMBH	
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City:	GARCHING	
State/Country:	GERMANY	
Postal Code:	85748	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	14556298
CORRESPONDENCE DATA		
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SIGNATURE:	/John E. Kind/	
DATE SIGNED:	12/16/2015	
Total Attachments: 6		
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ASSIGNMENT OF PATENTS AND PATENT APPLICATIONS

Whereas, SUSS MICROTEC INC, a US Company, having a place of business at 228 Suss Dr., Waterbury Center, VT 05677 (hereinafter, called "Assigner") is the owner of the following patents, applications and inventions:

Docket No.	Title	Type	Patent filed	Application No.	Patent No.	Inventors
SU-103UA	APPARATUS AND METHOD FOR IN-SITU MONITORING OF WAFER BONDING TIME	US utility	5/10/08	12/118,100	7612895	M. Gabriel, M. Stiles
SU-103PCT	APPARATUS AND METHOD FOR IN-SITU MONITORING OF WAFER BONDING TIME	PCT	5/10/08	PCT/US2008/063347		M. Gabriel, M. Stiles
SU-104UA	APPARATUS AND METHOD FOR SEMICONDUCTOR BONDING	US utility	6/21/07	11/766,531		G. George, E. Hancock, R. Campbell
SU-104PCT	APPARATUS AND METHOD FOR SEMICONDUCTOR BONDING	PCT	6/22/07	PCT/US0771857		G. George, E. Hancock, R. Campbell
SU-105UA	APPARATUS AND METHOD	US utility	4/1/09	12/416,779		G. George

Docket No. SU-General

	FOR SEMICONDU CTOR ALIGNING					
SU- 105PCT	APPARATUS AND METHOD FOR SEMICONDU CTOR ALIGNING	PCT	4/2/09	PCT/US09/ 39238		G. George
SU- 106UA	IMPROVED METHOD AND APPARATUS FOR WAFER BONDING	US utility	6/10/09	12/481,692		E. Hughlett, T. Price, H. Johnson
SU- 106PCT	IMPROVED METHOD AND APPARATUS FOR WAFER BONDING	PCT	6/11/09	PCT/US20 09/046967		E. Hughlett, T. Price, H. Johnson
SU- 107UA	METHOD AND APPARATUS FOR WAFER BONDING WITH ENHANCED WAFER MATING	US utility	11/16/09	12/618,846		G. George
SU- 107PCT	METHOD AND APPARATUS FOR WAFER BONDING WITH ENHANCED WAFER MATING	PCT	11/16/09	PCT/US09/ 64509		G. George
SU- 108UA	RAPID FABRICATIO N OF A MICROELEC TRONIC	US Utility	3/16/10	12/725,351		J. Moore J. Hermano wski

	TEMPORARY SUPPORT TO SUSTAIN SUBSTRATE THINNING AND BACKSIDE PROCESSING					
SU- 108PCT	RAPID FABRICATIO N OF A MICROELEC TRONIC TEMPORARY SUPPORT TO SUSTAIN SUBSTRATE THINNING AND BACKSIDE PROCESSING	PCT	3/17/10	PCT/US10/ 27560		J. Moore J. Hermano wski
SU- 109AU A	IMPROVED APPARATUS FOR TEMPORARY WAFER BONDING	US Utility	4/15/10	12/760,640		H. Johnson, P. Gorun, E. Hughlett, J. Hermano wski, M. Stiles, M. Kuhnle
SU- 109BU A	IMPROVED APPARATUS FOR TEMPORARY WAFER BONDING	US Utility	4/15/10	12/760,973		G. George, H. Johnson, P. Gorun, E. Hughlett, J. Hermano wski, M. Stiles,
SU- 109CU A	IMPROVED APPARATUS FOR TEMPORARY	US Utility	4/15/10	12/761,014		G. George, H. Johnson,

	WAFER BONDING					P. Gorun, J. Hermanowski, M. Stiles,
SU-109DUA	IMPROVED APPARATUS FOR TEMPORARY WAFER BONDING	US Utility	4/15/10	12/761,044		G. George, H. Johnson, D. Patricio
SU-109PCT	IMPROVED APPARATUS FOR TEMPORARY WAFER BONDING	PCT	4/14/10	PCT/US10/31302		G. George, H. Johnson, P. Gorun, E. Hughlett, J. Hermanowski, M. Stiles, M. Kuhnle, W. Bair, D. Patricio
SU-110UA	AUTOMATED THERMAL SLIDE DEBONDER	US Utility	12/22/10	12/975,521		J. HERMANOWSKI
SU-110PCT	AUTOMATED THERMAL SLIDE DEBONDER	PCT	12/22/10	PCT/US2010/061725		J. HERMANOWSKI
SU-111prov	IMPROVED DEBONDING EQUIPMENT AND METHODS FOR TEMPORARY BONDED WAFERS	provisional	4/16/10	61324888		G. George
SU-112UA	THIN WAFER CARRIER	US Utility	2/7/11	13/022,215		D. Hurley; G. George

SU-112PCT	THIN WAFER CARRIER	PCT	2/8/11	PCT/US2011/023961		D. Hurley; G. George
SU-113prov	APPARATUS FOR HIGH THROUGHPUT WAFER BONDING	provisional	4/12/10	61322980		G. George
SU-114prov	APPARATUS AND METHOD FOR DETAPING AN ADHESIVE LAYER FROM THE SURFACE OF ULTRA THIN WAFERS	provisional	5/27/10	61348794		G. George
C 451 US	Proximity mask alignment using stored image	US utility	2/7/92	07/832,413	5204739	P.L. Domenicali

And whereas SUSS MICROTEC LITHOGRAPHY, GmbH, a German Company, having a place of business at 90 Schleissheimer Str., 85748 Garching, Germany (hereinafter, called "Assignee"), desires to acquire the entire right, title and interest in said Patents, Applications and inventions, and to any United States and foreign patents to be obtained therefore;

Now therefore, for good and valuable consideration, receipt whereof is hereby acknowledged, Assigner hereby sells, assigns, and transfers to Assignee, its successors and assigns, the entire right, title and interest in said Patents, Applications and inventions therein disclosed for the United States and foreign countries, and all rights of priority

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resulting from the filing of said United States Applications, and Assigner requests the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said applications to Assignee, its successors and assigns; and Assigner hereby agrees that Assignee may apply for foreign Letters Patent on said inventions and Assigner will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by Assignee.

SUSS MICROTEC INC hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into, which would conflict with this assignment.

(1) Executed at SUNNYVALE, on MARCH 10th, 2011

(1) [Signature]

State of CALIFORNIA
County of Santa Clara

Before me personally appeared and acknowledged the foregoing instrument to be his free act and deed this 10th day of MARCH, 2011

Seal



[Signature]
Notary Public